508003000 07/11/2023

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE: ASSIGNMENT	

CONVEYING PARTY DATA

Name	Execution Date
JUNG HYE CHAE	02/01/2021

RECEIVING PARTY DATA

Name:	ROHM AND HAAS ELECTRONIC MATERIALS KOREA LTD.	
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City:	CHUNGCHEONGNAM-DO	
State/Country:	KOREA, REPUBLIC OF	
Postal Code:	31093	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	18219833

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NAME OF SUBMITTER:	DAVID M. LAPRAIRIE	
SIGNATURE:	/David M. LaPrairie/	
DATE SIGNED:	07/11/2023	

Total Attachments: 1

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PATENT 508003000 REEL: 064211 FRAME: 0482

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FORM 110 (R 5/97)

INDIVIDUAL ASSIGNMENT AND INVENTOR'S DECLARATION

(with Priority Rights)

I/we verily believe I am/we are the original, first and sole/joint inventor(s) of the subject matter which is embraced by and for which a patent is sought on the invention entitled: A UV CURABLE SILICONE COMPOSITION AND AN ENCAPSULANT OR A SHEET FILM THEREOF

which invention was made and invented by me/us out of and in the course of my/our employment with my/our respective employers as stated below my/our name(s). I/we acknowledge that I/we hold the invention and all patent and other rights and powers obtainable or exercisable in respect thereof in trust for our respective employers. As trustee(s), and for good and valuable consideration and/or the remuneration received for my/our work, I/we sell, assign and transfer unto:

Rohm and Haas Electronic Materials Korea Ltd. 56, 3-Gondan 1-ro. Seobuk-gu, Cheonan-si, Chungcheongnam-do, Republic of Korea 31093

an entity organized and existing under the laws of Japan (hereinafter referred to as the "Assignee"); my/our entire right, title and interest throughout the world, in and to the invention and all rights and powers to make applications, including provisional applications when permitted by law, for Letters Patent in its own name, or in the name of its designee (or nominee(s)); and all rights and powers to file any corresponding or equivalent applications in any and all countries, including all rights to claim priority under all United States domestic laws, International Convention(s) and Treaties in the name of Assignee, and do hereby authorize Assignee or its designee to insert here the Priority Number, Filing Date, and Filing Country

Priority Number	Filing Date	Filing Country
2020-033944	February 28, 2020	Japan

of the application, on which the claim for priority will be based; and in and to any Letters Patent that may be issued for the invention in any and all countries. I/we do hereby agree to assist Assignee in the prosecution of the application(s) and in any interference, conflict, opposition or litigation which may arise involving the invention or the patent or patents thereon, and to execute for any and all countries any document relating to applications derived from, corresponding to or equivalent to the above identified application as Assignee may request.

I/we authorize Assignee or its designee to translate this Assignment into all languages necessary: and we request that any such Letters Patent be issued to Assignee; and consent to the recordal of this Assignment, or a Notarial True Copy thereof, being under covenant not only that I/we have full power to make the same, but also that such assigned rights are not encumbered by any grant, license, or other right heretofore given.

Subscribed and Declared by me/us:

Att HWASEPMS: , Korea	At:
this day of	this day of .20
Effective as of February 26, 2620	
Signature:	Signature:
Full Name: Jung Hye Chae	Full Name:
Mailing Address: 20, Samsung 1-Ro 5-Gil, Hwaseong-Si,	Mailing Address:
Gyeonggi-Do 18449, Korea	Tradition of the state of the s
At:	At:
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Full Name:	Full Name:
Mailing Address:	Mailing Address:

PATENT REEL: 064211 FRAME: 0483